

WHAT IS CLAIMED IS:

Sub A1

1 A multilayered wiring substrate, comprising:

5 layers containing a signal wiring group made by a plurality of signal wirings disposed in parallel with one another; and

dummy wirings disposed outside said signal wiring group in parallel to said signal wirings, at least one of said dummy wirings being disposed at each side of said signal wiring group.

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2. The multilayered wiring substrate according to claim 1, further comprising:
through holes formed in a stacking direction of said wiring layers and disposed in each clearance between said signal wirings;

15 a dummy through hole extending in said stacking direction, disposed adjacent to said dummy wiring on the side on which said signal wiring group is present; and
conductive layers disposed inside said through holes and said dummy through hole, respectively.

20 3. The multilayered wiring substrate according to claim 2 wherein
said conductive layer in said dummy through hole is electrically connected to
said conductive layer in any one of said through holes.

25 4. The multilayered wiring substrate according to claim 2 wherein
said conductive layer in said dummy through hole is electrically connected to
said dummy wiring.

5. The multilayered wiring substrate according to claim 1, further comprising
at least one resistance having approximately the same impedance as a
characteristic impedance of said dummy wiring, and being electrically connected to an
5 end or central part of said dummy wiring.

6. The multilayered wiring substrate according to claim 1, further comprising
at least one terminal for connecting a terminating resistance connected
electrically to an end or central part of said dummy wiring.

Add A2

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